

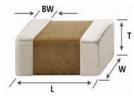
Specification of Automotive MLCC (Reference sheet)



- Supplier : Samsung Electro-Mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL05B331KB5VPNC
- Description : CAP, 330pF, 50V, ± 10%, X7R, 0402
- AEC-Q200 Qualified

A. Dimension





Size	0402 inch
L	1.00±0.05 mm
W	0.50±0.05 mm
Т	0.50±0.05 mm
BW	0.25±0.10 mm

B. Samsung Part Number

<u>CL</u>	<u>05</u>	<u>B</u>	<u>331</u>	<u>ĸ</u>	B	<u>5</u>	<u>v</u>	<u>P</u>	<u>N</u>	<u>c</u>
1	2	3	4	5	6	\bigcirc	8	9	10	1

1 Series	Samsung Multi-layer Ceramic Capacitor					
② Size	0402 (inch code)	L: 1.00±0.05 mm	W :0.50±0.05 mm			
③ Dielectric	X7R	⑧ Inner electrode	Ni			
Capacitance	330 pF	Termination	Metal-Epoxy			
⑤ Capacitance	± 10%	Plating	Sn 100% (Pb Free)			
tolerance		9 Product	Automotive			
Rated Voltage	50 V	Special code	Normal			
⑦ Thickness	0.50±0.05 mm	1 Packaging	Cardboard Type, 7" Reel			

C. Reliability Test and Judgement condition

Test items	Performance	Test condition		
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1,000hrs @ Max. temperature		
Exposure	Capacitance Change Within ±10 %	Measurement at 24±2hrs after test conclusion		
	Tan δ :0.03 max.			
	IR :More than 10,000 ^M Ω or 500 ^M Ω× <i>μ</i> F	Initial Measurement 2*		
	Whichever is smaller	Final Measurement 3*		
Temperature Cycling	Appearance : No abnormal exterior appearance	1,000Cycles		
	Capacitance Change Within ±10 %	Initial Measurement 2*		
	Tan δ :0.03 max.	Final Measurement 3*		
	IR : More than 10,000 M $_{\Omega}$ or 500 M $_{\Omega} \times \mu$ F	Measurement at 24±2hrs after test conclusion		
	Whichever is smaller	1 cycle condition : -55+0/-3 °C(30±3min) → Room Temp. (1min)		
		→ 125+3/-0 $^{\circ}$ C (30±3min) → Room Temp. (1min)		
Destructive Physical	No Defects or abnormalities	Per EIA 469		
Analysis				
Humidity Bias	Appearance : No abnormal exterior appearance	1,000hrs 85 °C/85%RH, Rated Voltage and 1.3~1.5V,		
	Capacitance Change Within ±12.5 %	Add 100kohm resistor		
	Tan δ :0.035 max.	Initial Measurement 2*		
	IR :More than 500 ^{MΩ} or 25 ^{MΩ} × <i>μ</i> F	Final Measurement 4*		
	Whichever is smaller	Measurement at 24±2hrs after test conclusion		
		The charge/discharge current is less than 50mA.		
High Temperature	Appearance : No abnormal exterior appearance	1,000hrs @ 125℃, 200% Rated Voltage,		
Operating Life	Capacitance Change Within ±12.5 %	Initial Measurement 2*		
	Tan δ :0.035 max.	Final Measurement 4*		
	IR :More than 1,000 ^M ♀ or 50 ^M ♀× <i>µ</i> F	Measurement at 24±2hrs after test conclusion		
	Whichever is smaller	The charge/discharge current is less than 50mA.		

	Performance	Test condition					
External Visual	No abnormal exterior appearance	Microscope ('10)					
Physical Dimension	Within the specified dimensions	Using The calipers					
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along					
	Capacitance Change Within ±10 %	3 mutually perpendicular axes of the test specimen (18 shocks)					
	Tan δ, IR : Initial spec.	Peak value Duration Wave Velocity					
		1,500G 0.5ms Half sine 4.7m/sec					
		Initial Measurement 2*					
		Final Measurement 5*					
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,					
	Capacitance Change Within ±10 %	Use 8"×5" PCB 0.031" Thick 7 secure points on one long side					
	Tan δ, IR : Initial spec.	and 2 secure points at corners of opposite sides. Parts mounted					
		within 2" from any secure point. Test from 10~2,000 $\mbox{Hz}.$					
		Initial Measurement 2*					
		Final Measurement 5*					
Resistance to	Appearance : No abnormal exterior appearance	preheating : 150℃ for 60~120 sec.					
Solder Heat	Capacitance Change Within ±10 %	Solder pot : 260±5℃, 10±1sec.					
	Tan δ, IR : Initial spec.	Initial Measurement 2*					
		Final Measurement 3*					
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002 or ISO/DIS10605					
	Capacitance Change Within ±10 %	Initial Measurement 2*					
	Tan δ, IR : Initial spec.	Final Measurement 4*					
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 $^\circ\!\!\!\!^\circ$ for 4 hours, Immerse in solder for 5s at 245±5 $^\circ\!\!\!^\circ\!\!\!^\circ$					
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245 ± 5 °C					
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260 \pm 5 $^{\circ}\mathrm{C}$					
		solder : a solution ethanol and rosin					
Electrical	Capacitance : Within specified tolerance	*A capacitor prior to measuring the capacitance is heat treated at					
Characterization	Tan δ :0.025 max.	150 +0/-10°C for 1hour and maintained in ambient air for 24±2 hours					
	IR(25℃): More than 10,000 ^M Ω or 500 ^M Ω×μ ^F	The Capacitance / D.F. should be measured at 25° C,					
	Whichever is smaller	$1 \text{ kHz} \pm 10\%$, $1 \pm 0.2 \text{ Vrms}$					
	IR(125°C) More than 1,000 M ^{Ω} or 10 M ^{Ω} × μ F	I.R. should be measured with a DC voltage not exceeding					
	Whichever is smaller	Rated Voltage @25°C, @125°C for 60~120 sec.					
	Dielectric Strength	Dielectric Strength : 250% of the rated voltage for 1~5 seconds					
Deerd Flow	Appearance : No abnormal exterior appearance	Bending to the limit, 3 mm for 60 seconds 1*					
Board Flex	Capacitance Change Within ±10 %	Initial Measurement 2*					
		Final Measurement 5*					
Terminal	Appearance : No abnormal exterior appearance	2 N, for 60 sec.					
Strength(SMD)	Capacitance Change Within ±10 %	Initial Measurement 2*					
Strength(SWD)		Final Measurement 5*					
Beam Load	Destruction value should be exceed 8 N	Beam speed : 0.5±0.05 mm/sec					
Temperature	X7R						
Characteristics	From -55 \degree to 125 \degree , Capacitance change shou	ld be within ±15%					

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260 +0/-5 °C, 30sec.), Meet IPC/JEDEC J-STD-020 D Standard

- *1 : The figure indicates typical specification. Please refer to individual specifications.
- *2 : Initial measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- *3 : Final measurement : Let sit for 24±2 hours at room temperature after test conclusion, then measure.
- *4 : Final measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- *5 : Final measurement : Let measure within 24 hours at room temperature after test conclusion.

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

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- Aerospace/Aviation equipment
- ② Medical equipment
- *③ Military equipment*
- ④ Disaster prevention/crime prevention equipment
- *5* Power plant control equipment
- 6 Atomic energy-related equipment
- ⑦ Undersea equipment
- ⑧ Traffic signal equipment
- Data-processing equipment
- 10 Electric heating apparatus, burning equipment
- ${\it I\!\! D}$ Safety equipment
- 2 Any other applications with the same as or similar complexity or reliability to the applications